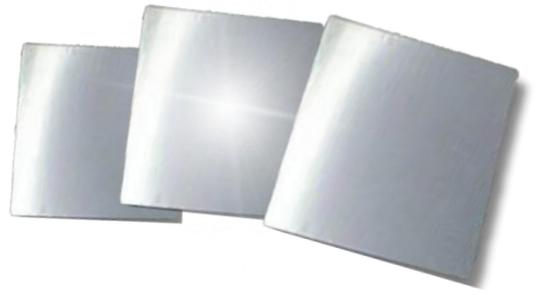


# 銅片及多層複合材



## Indium

低熱阻表現 (Low thermal resistance performance)

提供客製選項 (Customizable options available)

極高導熱性能材料 (Ultra-high thermal conductivity materials)

穩定性與可靠度高 (High stability and reliability)

柔軟順貼 · 能緊密服貼各種表面 (Soft and conformable to tightly adhere to various surfaces)

金屬導熱片 Metal Thermal Pad

Property	GIN-81	GIN-80	GIN-75	GIN-70	GIN-35
Composition 成分	In	In + Sn	In + Ag	In + Sn	In+Bi+Sn
Melting Point 熔點 °C	156	150	143	118	60
Thermal Conductivity 熱導率 (W/mK)	81	80	80	71	35
Thermal Resistance 熱阻 (Kcm <sup>2</sup> /W)	0.15 0.2mm,80psi	0.15 0.2mm,80psi	0.17 0.2mm,80psi	0.19 0.2mm,80psi	0.04~0.06
Electrical Conductivity 導電率	11.6	11.1	11.1	9.8	5
Operating Temp 工作溫度	-50~150	-50~150	< 100	-50~110	< 100
Surface 表面	光面、單/雙面網紋、菱形網紋、圓點網紋				
Dimensional Range 尺寸範圍	寬度5~400mm · 厚度0.05~10mm,長度可客製				

多層複合材料  
Multi-Layered Composite

GIN-C62	GIN-C72
LMPA + IN + LMPA	
62	72
70	70
≤0.05(50psi)	≤0.05(50psi)
10	10
-40~150	-40~150
光面、單/雙面網紋、菱形、條形、圓點	
寬度5~150 厚度0.05~1mm	

